



#### FABRICATION NOTE:

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVLSRK1000 SOT23 DPAK R1 FOR CIRCUIT PATTERN  
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN  
APPROVAL FROM AN AUTHORIZED IFARCAD SRL REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH  
APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND  
PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 125 C  
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:GREEN SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF  
OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE  
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD  
FABBRICATION STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON  
OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION  
TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON  
SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	12.0	PLATED	13
B	44.0	PLATED	3
TOTAL HOLES: 16			

Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008"-0.013"	+0.002/-FHS"	+/-0.002"
0.014"-0.063"	+/-0.003"	+/-0.002"
0.064"-0.156"	+/-0.004"	+/-0.003"
0.157"-0.250"	+/-0.007"	+/-0.004"
0.251"and up	+/-0.007"	+/-0.005"
0.125"	Non Plated Only	+0.003/-0.000"

#### DETAIL 'A'

LAYER BUILD UP  
(reference only)

	Cu - 105u
	CORE - 1600u
	Cu - 105u

(external Cu th are after plating)  
estimated total thickness 1600u

REVISION DATE									
		Description  <b>SRK1000-SOT23-DPAK FABRICATION DRAWING</b>						Symbol <b>SRK1000</b>	
								Group	
ALL RIGHTS STRICTLY RESERVED. REPRODUCTION OR ISSUE TO THIRD PARTIES IN ANY FORM WHATEVER IS NOT PERMITTED WITHOUT WRITTEN AUTHORIZATION FROM STMicroelectronics.		TOLERANCE UNLESS NOTED UNIT=MM				ISO	SCALE:	REV. <b>1.0</b>	
		linear	0 <10	>10 <50	>50 <200	>200	ANG. LES.	Material	
Drawn	date <b>23-June-2017</b>	midle	±0.1	±0.2	±0.3	±0.5	±1°	Treatment and surface finishing	
Approved	date	accurate	±0.05	±0.1	±0.15	±0.25	±30°		